

## TN1205T-600

#### **12 A SCR**

#### **Features**

■ High current density per square mm

#### **Applications**

- Overvoltage crowbar protection
- Motor control circuits in power tools and kitchen aids
- Inrush current limiting circuits

#### **Description**

This device is mounted in DPAK and intended for use in applications such as voltage regulators circuits for motorbikes, overvoltage crowbar protection, motor control circuits in power tools and capacitive discharge ignition.

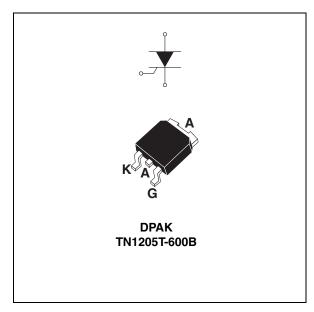


Table 1. Device summary

I <sub>T(rms)</sub>	12 A
V <sub>DRM</sub> /V <sub>RRM</sub>	600 V
I <sub>GT</sub>	2 to 5 mA

Characteristics TN1205T-600

## 1 Characteristics

Table 2. Absolute ratings<sup>(1)</sup>

Symbol	Parameter Parameter				Unit
I <sub>T(RMS)</sub>	On-state rms current (180 °C conduction angle)		T <sub>c</sub> = 103 °C	12	Α
I <sub>T(AV)</sub>	Average on-state current(180 °C conduction angle) T <sub>c</sub> = 103 °C			8	Α
I <sub>TSM</sub>	Non repetitive surge peak on-state current $ t_p = 8.3 \text{ ms} $ $ t_p = 10 \text{ ms} $			120 115	Α
I <sup>2</sup> T	$I^2T$ value for fusing $t_p = 10 \text{ ms}$		t <sub>p</sub> = 10 ms	66	A <sup>2</sup> s
di/dt	Critical rate of rise of on-state current $I_G = 2 \times I_{GT}$ , tr $\leq 100 \text{ ns}$	F = 60 Hz	T <sub>j</sub> = 125 °C	50	A/µs
I <sub>GM</sub>	Peak gate current $t_p = 20 \mu s$		T <sub>c</sub> = 125 °C	4	Α
P <sub>G(AV)</sub>	Average gate power dissipation $T_j = 125 ^{\circ}\text{C}$			1	W
T <sub>stg</sub>	Storage junction temperature range			-40 to + 150	°C
T <sub>j</sub>	Operating junction temperature range			-40 to + 125	J

<sup>1.</sup>  $T_j = 25$  °C, unless otherwise specified

Table 3. Electrical characteristics<sup>(1)</sup>

Symbol	ol Test conditions			Тур.	Max.	Unit
I <sub>GT</sub>	$V_D = 12 \text{ V}, R_L = 33 \Omega$		2		5	mA
V <sub>GT</sub>	$V_D = 12 \text{ V}, \text{ R}_L = 33 \Omega$				1.3	V
$V_{GD}$	$V_D = V_{DRM}, R_L = 3.3 \text{ k}\Omega$	T <sub>j</sub> = 125 °C	0.2			V
I <sub>H</sub>	I <sub>T</sub> = 500 mA gate open				15	mA
ΙL	I <sub>G</sub> = 1.2 I <sub>GT</sub>				30	mA
dV/dt	V <sub>D</sub> = 67% V <sub>DRM</sub> gate open	T <sub>j</sub> = 125 °C	100			V/µs
t <sub>GT</sub>	Gate controlled turn on time $I_{TM}=40~A,~V_D=V_{DRM(MAX)},~I_{GT}=100~mA$ $dI_G/dt=5~A/\mu s,~R_G=68~\Omega$			1.2		μs
t <sub>q</sub>	Circuit commutated turn off time V <sub>D</sub> = 67% V <sub>DRM(MAX)</sub> , T <sub>j</sub> = 125 °C, I <sub>TM</sub> = 20 A, V <sub>R</sub> = 25 V dI <sub>T</sub> /dt = 30 A/ $\mu$ S, dV <sub>D</sub> /dt = 50 V/ $\mu$ s, R <sub>GK</sub> = 100 $\Omega$			55		μs
$V_{TM}$	$I_{TM} = 24 \text{ A}, T_p = 380 \ \mu \text{s}$				1.6	V
V <sub>T0</sub>	Threshold voltage	T <sub>j</sub> = 125 °C			0.85	V
R <sub>d</sub>	Dynamyc restistance	T <sub>j</sub> = 125 °C			30	mΩ
I <sub>DRM</sub>	V V	T <sub>j</sub> = 25 °C			5	μΑ
I <sub>RRM</sub>	$V_{DRM} = V_{RRM}$				2	mA

<sup>1.</sup>  $T_j = 25$  °C, unless otherwise specified

TN1205T-600 Characteristics

Table 4. Thermal resistance

Symbol	Parameter		Value	Unit
R <sub>th(j-c)</sub>	Junction to case (DC)		1.8	°C/W
R <sub>th(j-a)</sub>	Junction to ambient (DC)	$S^{(1)} = 0.5 \text{ cm}^2$	70	°C/W

<sup>1.</sup> S = Copper surface under tab.

Figure 1. Maximum average power dissipation versus average on-state current

Figure 2. Average and DC on-state current versus case temperature

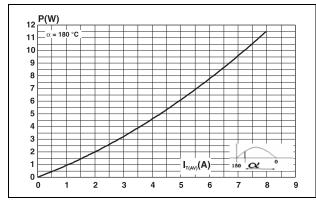
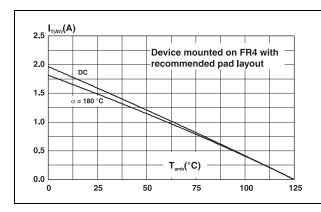
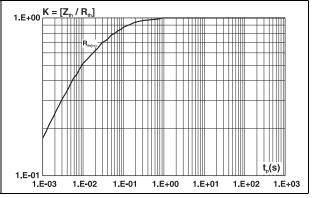


Figure 3. Average DC on-state current versus ambient temperature

Figure 4. Relative variation of thermal impedance junction to case versus pulse duration





Characteristics TN1205T-600

Figure 5. Relative variation of thermal impedance junction to ambient versus pulse duration

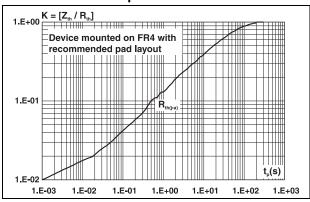


Figure 6. Relative variation of gate trigger current and voltage, holding and latching current versus T<sub>i</sub>

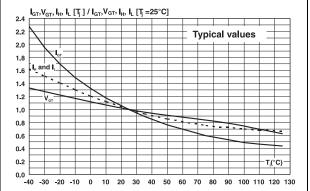
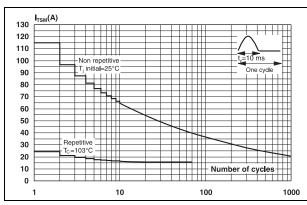


Figure 7. Surge peak on-state current versus number of cycles

Figure 8. Non-repetitive surge peak on-state current for a sinusoidal pulse, and corresponding values of l<sup>2</sup>t



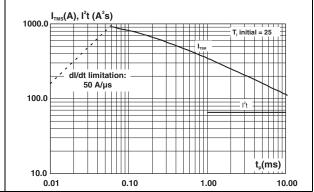
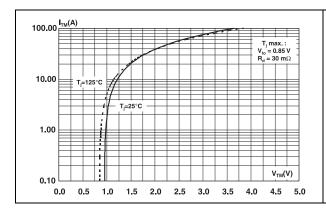
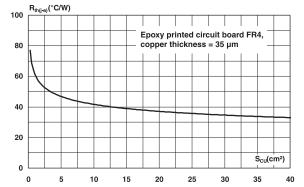


Figure 9. On-state characteristics (maximum values)

Figure 10. Thermal resistance junction to ambient versus copper surface under tab

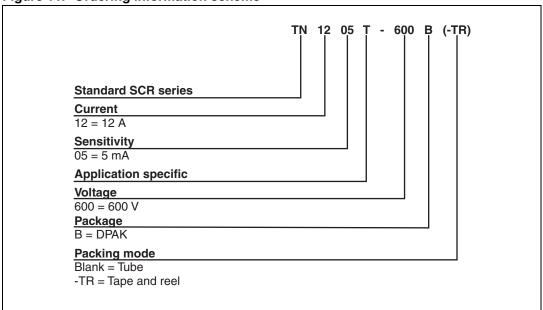




57

## 2 Ordering information scheme

Figure 11. Ordering information scheme





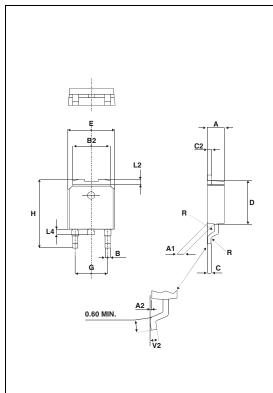
Package information TN1205T-600

## 3 Package information

- Epoxy meets UL94, V0
- Lead-free package

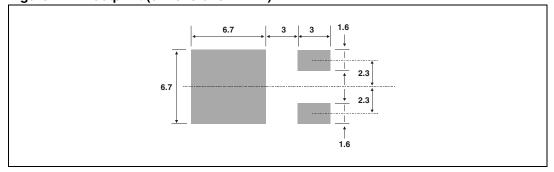
In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: <a href="https://www.st.com">www.st.com</a>. ECOPACK<sup>®</sup> is an ST trademark.

Table 5. DPAK dimensions



	Dimensions			
Ref.	f. Millimeters		Inc	hes
	Min.	Max.	Min.	Max.
Α	2.20	2.40	0.086	0.094
A1	0.90	1.10	0.035	0.043
A2	0.03	0.23	0.001	0.009
В	0.64	0.90	0.025	0.035
B2	5.20	5.40	0.204	0.212
С	0.45	0.60	0.017	0.023
C2	0.48	0.60	0.018	0.023
D	6.00	6.20	0.236	0.244
Е	6.40	6.60	0.251	0.259
G	4.40	4.60	0.173	0.181
Н	9.35	10.10	0.368	0.397
L2	0.80 typ.		0.03	1 typ.
L4	0.60	1.00	0.023	0.039
V2	0°	8°	0°	8°

Figure 12. Footprint (dimensions in mm)



6/8 Doc ID 16339 Rev 1

# 4 Ordering information

Table 6. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
TN1205T-600B	TN12 05T6	DPAK 0.3a		75	Tube
TN1205T-600B-TR	TN12 05T6	DEAR	DPAK 0.3g		Tape and reel

# 5 Revision history

Table 7. Document revision history

Date	Revision	Changes
01-Oct-2009	1	Initial release.

#### Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

UNLESS EXPRESSLY APPROVED IN WRITING BY AN AUTHORIZED ST REPRESENTATIVE, ST PRODUCTS ARE NOT RECOMMENDED, AUTHORIZED OR WARRANTED FOR USE IN MILITARY, AIR CRAFT, SPACE, LIFE SAVING, OR LIFE SUSTAINING APPLICATIONS, NOR IN PRODUCTS OR SYSTEMS WHERE FAILURE OR MALFUNCTION MAY RESULT IN PERSONAL INJURY, DEATH, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE. ST PRODUCTS WHICH ARE NOT SPECIFIED AS "AUTOMOTIVE GRADE" MAY ONLY BE USED IN AUTOMOTIVE APPLICATIONS AT USER'S OWN RISK.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2009 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Philippines - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com

8/8 Doc ID 16339 Rev 1

